ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Compo © Copyright 2005. IPo international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						erials and M	ials and Mfg Information				
Supplier Inform	nation																
Company name* Company			Company un	mpany unique ID			Unique ID Authority					Respon	Response Date*				
onsemi													2024-05-20				
Contact Name		Title - Contact			]	Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stew	ards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
uthorized Repres	entative*	Title - Representative			]	Phone - Representative*					Email -	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com				
Request	er Item Number			Item Number Mfr Item Name			Effective Da	ate V	Version Ma		Manufacturing Site		Weigh	nt*	UOM	Unit Type	
				Low-Side Gate Driver SO8			2024-05-20	00 TH2			80.792		mg	Each			
<b>Ianufacturing</b>	Proccess Informati	ion		,													
Terminal	Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 M	0-020 MSL Rating		Peak Process Body Temperature		ture N	re Max Time at Peak Tempera		ature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		С		30 seco		ds	3			
Comments																	
TTENTION: MS	L 3 Rated item requires	Bake and I	Ory Pack (after	electrical test)													
or more informati	on regarding material c	omposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.16	mg	Supplier	Silicon (Si)	7440-21-3		2.16	mg
Die Attach	1.144	mg	Supplier	Silver (Ag)	7440-22-4		0.8466	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.2974	mg
Lead Frame	31.571		Supplier	Silver (Ag)	7440-22-4		0.007	mg
			Supplier	Zinc (Zn)	7440-66-6		0.039	mg
			Supplier	Palladium (Pd)	7440-05-3		0.015	mg
			В	Nickel (Ni)	7440-02-0		0.404	mg
			Supplier	Gold (Au)	7440-57-5		0.009	mg
			Supplier	Iron (Fe)	7439-89-6		0.732	mg
			Supplier	Copper (Cu)	7440-50-8		30.339	mg
			Supplier	Phosphorus (P)	7723-14-0		0.026	mg
Mold Compound-Black	45.29		Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.83	mg
			Supplier	Carbon Black (C)	1333-86-4		0.09	mg
			Supplier	Silica (SiO2)	14464-46-1		39.42	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.95	mg
Wire Bond - Au	0.627	mg	Supplier	Gold (Au)	7440-57-5		0.627	mg